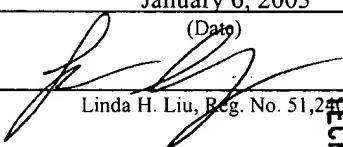




GP/2826
PATENT

Case Docket No. MICRON.240A
Date: January 6, 2003
Page 1

In re application of : Derraa et al.) I hereby certify that this correspondence and all marked
App. No. : 09/944,903) attachments are being deposited with the United States
Filed : August 30, 2001) Postal Service as first class mail in an envelope addressed
For : HIGH ASPECT RATIO) to: United States Patent and Trademark Office, P.O. Box
CONTACT STRUCTURE) 2327, Arlington, VA 22202, on
WITH REDUCED SILICON)
CONSUMPTION)
Examiner : Victor A. Mandala)
Art Unit : 2826)
)

January 6, 2003
(Date)

Linda H. Liu, Reg. No. 51,240

UNITED STATES PATENT AND TRADEMARK OFFICE
P.O. Box 2327
Arlington, VA 22202

ATTN: BOX NON-FEE AMENDMENT

Sir:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated as shown below:

CLAIMS AS FILED

CLAIMS REMAINING AFTER AMENDMENT	HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total Claims 18 — 26		= 0 ×	\$18	= \$0
Independent Claims 2 — 3		= 0 ×	\$84	= \$0
If application has been amended to contain multiple dependent claim(s), then add			\$280	= \$0
Time Extension Fee				\$0
		TOTAL ADDITIONAL FEE FOR THIS AMENDMENT		\$0

(X) Return prepaid postcard.
(X) Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.

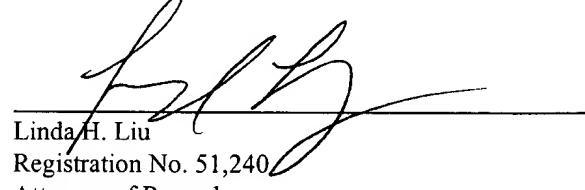
RECEIVED
JAN 13 2003
TECHNOLOGY CENTER 2800

Case Docket No. MICRON.240A

Date: January 6, 2003

Page 2

(X) Please use Customer No. 20,995 for the correspondence address.



Linda H. Liu
Registration No. 51,240
Attorney of Record
Customer No. 20,995
(909) 781-9231

R:\DOCS\LHL\LHL-4608.DOC:kmb
010603

MICRON 240A



#9
Amott B
DSmalls Logos
PATENT
11503

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	:	Derraa et al.)	Group Art Unit 2826
Appl. No.	:	09/944,903)	
Filed	:	August 30, 2001)	
For	:	HIGH ASPECT RATIO CONTACT STRUCTURE WITH REDUCED SILICON CONSUMPTION)	
Examiner	:	Victor A. Mandala)	

RECEIVED
JAN 13 2003
TECHNOLOGY CENTER 2800

AMENDMENT

United States Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

Dear Sir:

In response to the Office Action mailed October 4, 2002, please amend the above captioned application as follows:

IN THE CLAIMS:

Please amend the claims as follows:

1. (Amended) An integrated circuit, comprising:

a silicon substrate;

an insulating layer formed on an upper surface of the substrate wherein a contact opening is formed in the insulating layer, wherein the contact opening extends from an upper surface of the insulating layer to the upper surface of the substrate;

a conductive contact deposited in the opening in a manner such that the conductive contact directly contacts the upper surface of the substrate, wherein the conductive

B1